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PP8 Precision Lapping & Polishing Jigs

Description:

PP8 jigs are lightweight, sturdy and easy to maintain. Specifically with the 6" GaAs wafer backthinning system, the PP8 jig enables achieve industry standard Total Thickness Variation (TTV) without damaging the sample, while the standard support pillars and lift that the PP8 is easy to handle.

PP8 jigs allow 6" wafers to be held securely on a vacuum chuck and polished using the LP600 Precision Lapping and Polishing System. The removal indicator specifies the wafer thickness to within 1 μm .

The optional Programmable Sample Monitor (PSM) allows the user to process wafers to a pre-determined, programmed thickness while continuously supervising the process. Material to be removed is monitored by the PSM unit and is digitally displayed to within 1 mm, whilst an audible alarm sounds once the wafer has reached its preset level of thickness. The wafer need not be constantly supervised during processing.

An optional automatic cut-out, available with the PSM, switches the machine off once the preset wafer thickness has been reached. Should the process need to be interrupted, both the thickness level already reached and the preset value are stored in the monitor unit. Integral rechargeable batteries guarantee at least 18 hours operating time between recharges.

Applications: Geology, III-V Semiconductor, Silicon, Laser Fiber Optics, Ceramics, Organic Tissue

Equipment Type: Lapping, Polishing

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